



FOR IMMEDIATE RELEASE

LEADING MEMORY CHIP MANUFACTURER PURCHASES MULTIPLE VEECO AP300 LITHOGRAPHY SYSTEMS FOR DRAM INTERCONNECT APPLICATIONS

Growing Demand for Advanced Packaging in the Memory Market Highlights Value of Veeco's High Volume Manufacturing Lithography Systems

PLAINVIEW, New York, July 9, 2018 – [Veeco Instruments Inc.](#) (Nasdaq: VECO) today announced that one of the world's leading memory chip manufacturers has ordered multiple [AP300™](#) lithography systems to support the fast growing demand for DRAM with copper (Cu) pillars. The company selected the Veeco tools for their versatility in addressing advanced packaging applications, proven reliability in supporting high volume manufacturing and low total cost of ownership.

This approach echoes a larger industry trend, with more and more memory manufacturers exploring the use of Cu pillars in DRAM interconnect applications due to their higher input/output (I/O) density, improved electrical performance and better thermal efficiency. "Within the DRAM market, the interconnect is shifting from wire bond to flip chip," said Jan Vardaman, president of semiconductor packaging analyst firm TechSearch International, Inc. "We project that over the next three years, the annual number of flip chip interconnects in DRAM will grow 29 percent on a unit volume basis."

The AP300 is part of a family of lithography systems built on Veeco's customizable Unity Platform™, which delivers superior overlay, resolution and side wall profile performance, driving highly automated, cost-effective manufacturing for customers. The system is particularly well suited for Cu pillar, fan-out, through-silicon via (TSV) and silicon interposer applications. A low risk, low cost, high volume manufacturing solution, the AP300 is staged to support rapid market adoption of advanced packaging applications among memory manufacturers.

"The growing demand for innovative, alternative solutions to wire bonding in memory presents a strong opportunity for Veeco," said Rezwana Lateef, vice president and general manager of lithography products at Veeco. "Furthermore, this significant customer adoption validates the AP300's ability to address advanced packaging applications in a broader high-volume production market. To meet this demand, we are strengthening our regional technical staff to support numerous memory manufacturers looking to fast-track adoption."

Veeco will be at Booth #6070 at SEMICON West in San Francisco, CA, July 10-12, 2018.

About Veeco

Veeco (NASDAQ: VECO) is a leading manufacturer of innovative semiconductor process equipment. Our proven MOCVD, lithography, laser annealing, ion beam and single wafer etch and clean technologies play an integral role in producing LEDs for solid-state lighting and displays, and in the fabrication of advanced semiconductor devices. With equipment designed to maximize performance, yield and cost of ownership, Veeco holds technology leadership positions in all these served markets. To learn more about Veeco's innovative equipment and services, visit www.veeco.com.

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